

Performance

Positioning accuracy	±10μm(6σ)
Printing accuracy	±18μm(6σ)
Cycle time	8.5 sec + Printing time
Product changeover time	3 min or less
New product set-up time	10 min or less

Board handling

Max. Size (L x W)	510 mm x 510 mm
Min. Size (L x W)	50 mm x 50 mm
Thickness	0.4~6 mm
PCB thickness adjustment	Automatic
PCB Max. Weight	5kg
PCB edge clearance	3 mm
PCB bottom clearance	23 mm
PCB warpage	Max. 1% diagonally
Clamping method	Auto retractable top clamp, motor controlled side clamp
Support method	Magnetic support pins, bars, blocks, vacuum suction
Conveyor direction	L to R, R to L, R to R, L to L (software control)
Conveyor height	900 ± 40 mm
Conveyor speed (max.)	1,000 mm/s
Conveyor width adjustment	Automatic

Optical system

Field-of-View (FOV)	10mm x 8mm
Fiducial types	Circle, triangle, square, diamond, cross
Fiducial size	0.5~4.0 mm
Vision methodology	Digital CCD camera look up & down
2D inspection	Max.100 windows (10mmx8mm) to inspect missing & insufficient

Printing parameters

Stencil frame size (L x W)	Adjustable, 470 x 370 mm to 737 x 737 mm
Print gap	0~20 mm
Printing table adjustment range	X: ±10 mm, Y: ±10 mm θ: ± 2°
Print speed	10~200 mm/s
Squeegee pressure	0~10kg (program control)
Cleaning system	Auto wet, dry, vacuum (Software select)

Squeegee type

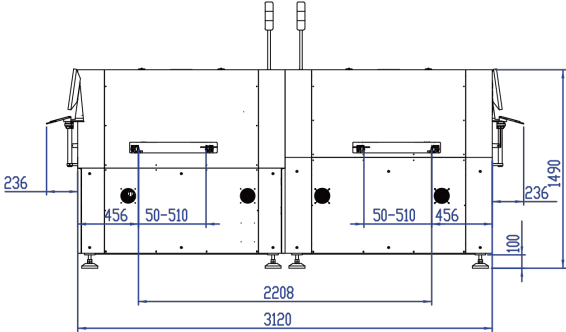
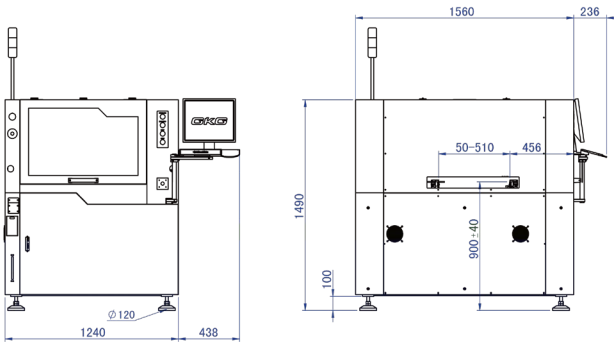
Metal squeegee	210mm, 280mm, 350mm, 420mm, 520mm
Rubber squeegee	210mm, 280mm, 350mm
Squeegee angle	Std. 60°

Facilities requirement

Power supply	Single-phase AC200V~240V 50/60Hz
Power consumption	3kW
Air supply	0.4 ~0.6MPa/cm²
Air consumption	5L/min
Dimension (excluding signal tower)	1,240 (L) x 1,560 (W) x 1,490 (H)
Machine weight	1,200kg

Operator interface

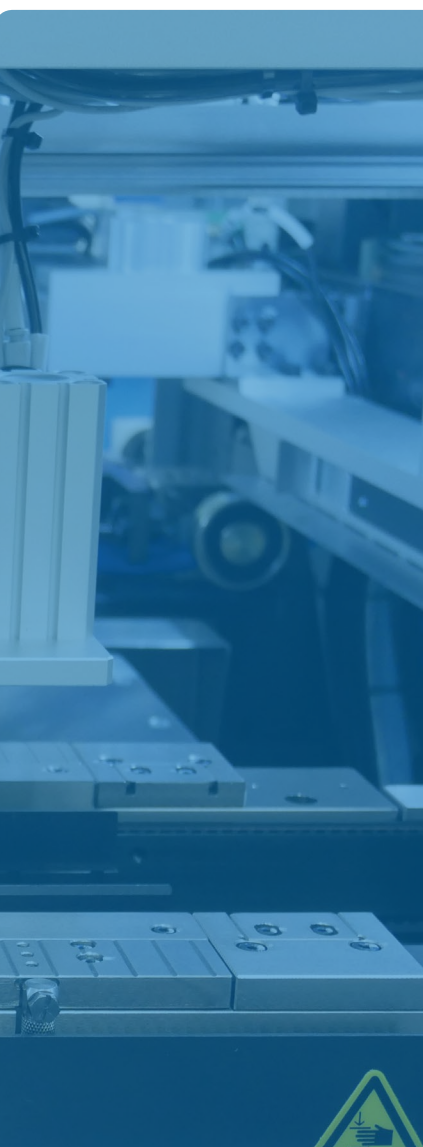
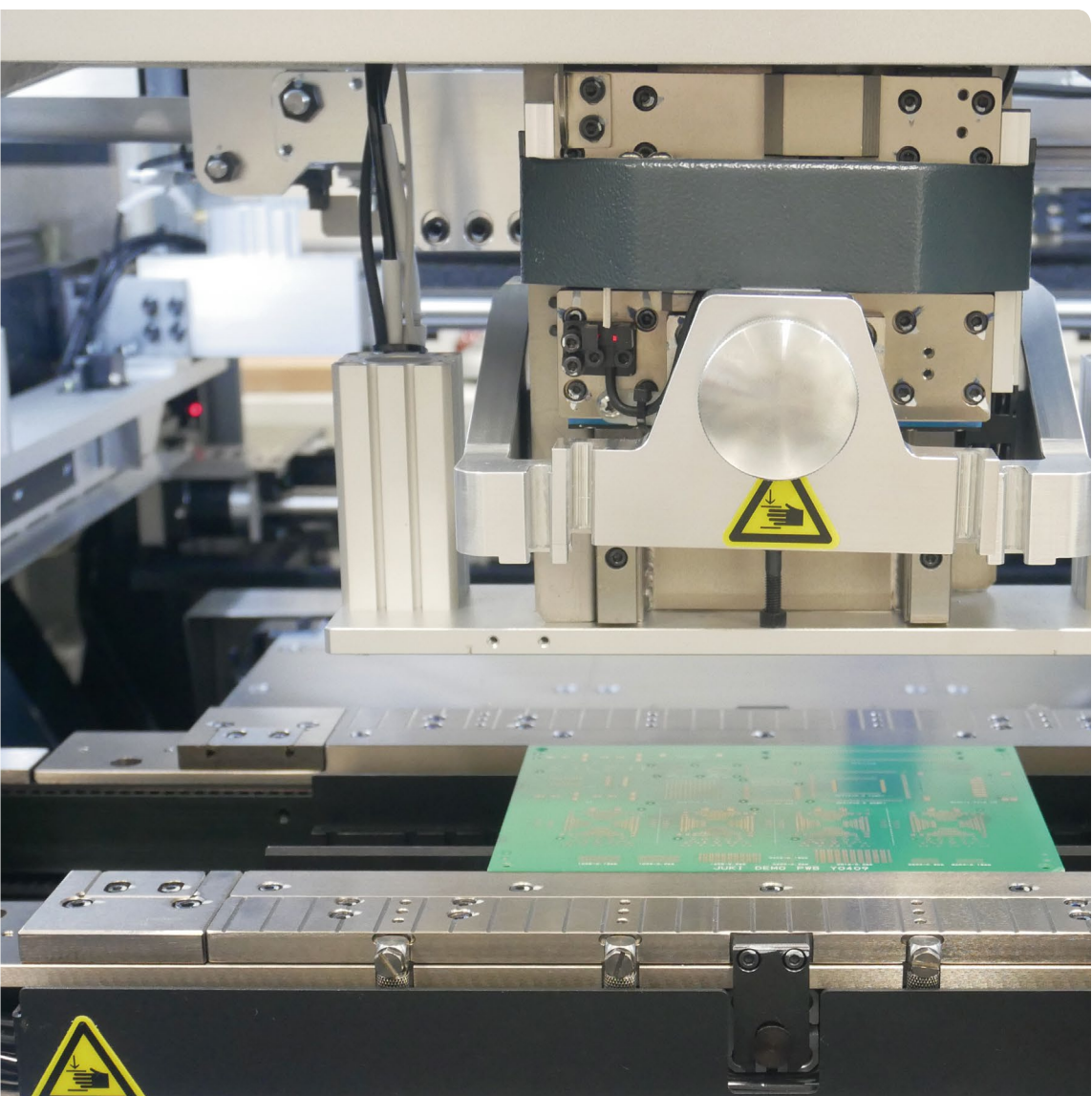
Hardware	LCD Monitor, Mouse & Keyboard
Operating system (OS)	Windows 7
Control method	Industrial PC controlled
I/O Interface	SMEMA Standard



Solder Paste Printer
RP-2(HP)/RP-2(B)



High Precision Solder Paste Printer with excellent cost performance



*Please refer to the product specifications for details.
■JUKI Specifications and appearance may be changed without notice.

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High Precision Solder Paste Printer with excellent cost performance



Solder Paste Printer

Multi-function model

RP-2(HP)

Basic model

RP-2(B)

PCB size : 50×50 mm - 510×510 mm

Cycle time : 8.5 sec+Printing time

Positioning accuracy : ±10μm(6σ)

Printing accuracy : ±18μm(6σ)

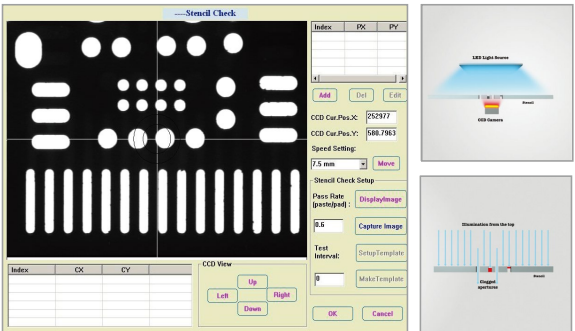
Stencil frame size : 735 ×735 mm/t : 30 mm

Quality Print Control (QPC) - Nothing is more important than a GOOD print

Stencil aperture inspection system

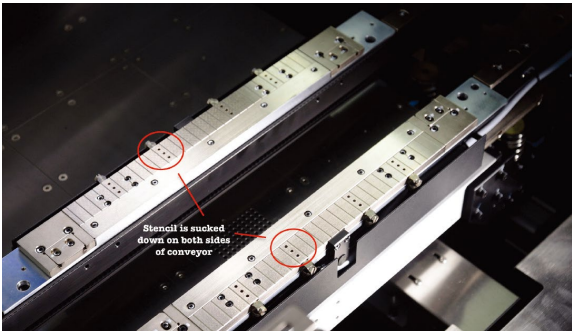
HP

Using panel light installed at the top and CCD camera below to inspect stencil apertures. It automatically detects the clogging of stencil apertures to eliminate poor quality stencil being used, ensure quality printing right from the start.



The Stencil lock & PCB clamber

The Stencil lock sucks the stencil firmly on both sides of the conveyor during printing cycle. To eliminate stencil vibration by having firm contact with PCB. The PCB clamber is a combination of retractable top clamp and motor controlled side clamp, uniquely designed by GKG (patented). With these standard features, all of today' s available and challenging substrates can be securely clamped and print to the highest quality.



SPI Close-loop connection

With SPI close-loop system, machine will automatically adjust and correct the print deposits based on the feedback given with regards to poor printing quality. This will facilitate improved print quality and production efficiency, by forming a complete printing feedback system.

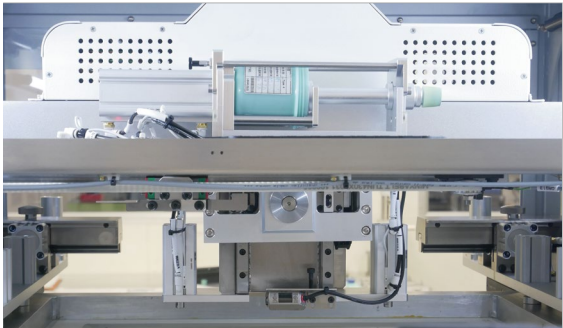


Optimum-Paste Control (OPC) - Get ready for lights - out manufacturing

Auto solder paste replenishment system

HP

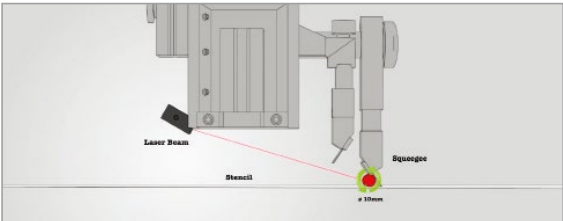
The solder paste is automatically dispensed across the entire squeegee length, maintaining at 15 mm rolling diameter, adopting the common 500 grams' solder paste jar. Completely eliminates the wastage of solder paste overflowing to the sides of squeegee.



Solder paste rolling diameter monitoring system

HP

Tracing solder paste rolling diameter in real time and trigger the auto dispensing if it falls below 10 mm. Completely eliminate insufficient solder paste on stencil and keep the paste rolling speed within optimum range to achieve best printing result.



Specifications, Options (S: Standard, O: Option, N/A: Not Applicable)

Features	RP-2 (HP)	RP-2 (B)	Features	RP-2 (HP)	RP-2 (B)
Metal squeegee 210, 350 mm	S	S	Printing table vacuum system	S	S
Metal squeegee 280, 420, 520 mm	O	O	Auto paste dispensing (rear mounting)	S	N/A
Rubber squeegee 210, 280, 350 mm	O	O	Paste rolling diameter monitoring system	S	N/A
Stencil lock	S	S	Temperature humidity monitoring & display	S	N/A
Auto table adjustment for pcb thickness	S	S	Internal barcode scanner for pcb traceability	O	N/A
Support block hit prevention system	S	S	Hand held scanner	O	O
Stencil y-direction position memory	S	S	Stencil aperture inspection system	S	N/A
Support pins set	S	S	Spi closed-loop	O	O
Support blocks set	S	S	2D Inspection (Max. 100 point)	S	S